

Product Change Notification - GBNG-09EAUN458

Date:

14 Aug 2018

Product Category:

Ethernet PHYs

Affected CPNs:

Notification subject:

CCB 3473 Initial Notice: Qualification of ASE as a new assembly site for selected Micrel KSZ8061 device family available in 48L VQFN (7x7x0.9 mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:
PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel KSZ8061 device family available in 48L VQFN (7x7x0.9 mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at TICIP.

Post Change:

Assembled at ASE.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp (TICP)	ASE Inc. Taiwan (ASE)
Wire material	CuPdAu	CuPdAu
Die attach material	EN4900	EN4900
Molding compound material	G631	G631
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying ASE as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

January 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen



business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	August 2018					-->	January 2019				
	31	32	33	34	35		01	02	03	04	05
Initial PCN Issue Date			X								
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 14, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-09EAUN458_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

GBNG-09EAUN458 - CCB 3473 Initial Notice: Qualification of ASE as a new assembly site for selected Micrel KSZ8061 device family available in 48L VQFN (7x7x0.9 mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Affected Catalog Part Numbers (CPN)

KSZ8061MNGW

KSZ8061MNGW-TR